



**TM08N02AF3**

**N-Channel Enhancement Mosfet**



**General Description**

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

**Applications**

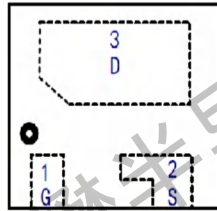
- Load switch
- PWM

**General Features**

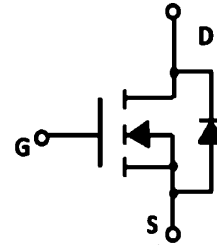
$V_{DS} = 20V$   $I_D = 8.0A$   
 $R_{DS(ON)} = 12m\Omega$  (typ.) @  $V_{GS}=4.5V$

100% UIS Tested  
 100%  $R_g$  Tested

AF3: DFN1.5x1.5-3L



Marking: 08N02



**Absolute Maximum Ratings ( $T_A=25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS}$ @ 4.5 V	8	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS}$ @ 4.5 V	5	A
$I_{DM}$	Pulsed Drain Current	28	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation	1.3	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	168	$^\circ C/W$

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**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V,$	-	-	1.0	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.7	0.9	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note2</small>	$V_{GS}=4.5V, I_D=5.6A$	-	12	15	m $\Omega$
		$V_{GS}=2.5V, I_D=4.5A$	-	16	23	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=10V, V_{GS}=0V,$ $f=1.0MHz$	-	905	-	pF
$C_{oss}$	Output Capacitance		-	182	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	164	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=10V, I_D=5.6A,$ $V_{GS}=4.5V$	-	11	-	nC
$Q_{gs}$	Gate-Source Charge		-	2	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	3.8	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10V,$ $I_D=5.6A, R_{GEN}=6\Omega,$ $V_{GS}=4.5V$	-	367	-	ns
$t_r$	Turn-on Rise Time		-	1337	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	4697	-	ns
$t_f$	Turn-off Fall Time		-	3037	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	8	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	28	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=7A$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

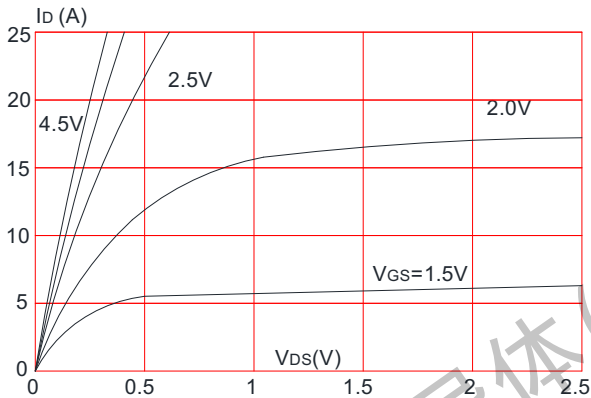
 2. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

**TM08N02AF3**

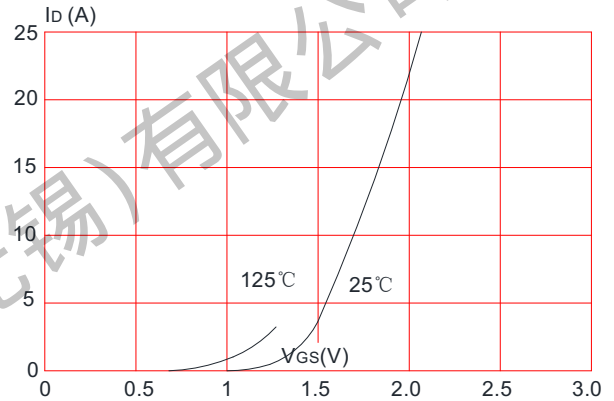
**N-Channel Enhancement Mosfet**

**Typical Performance Characteristics**

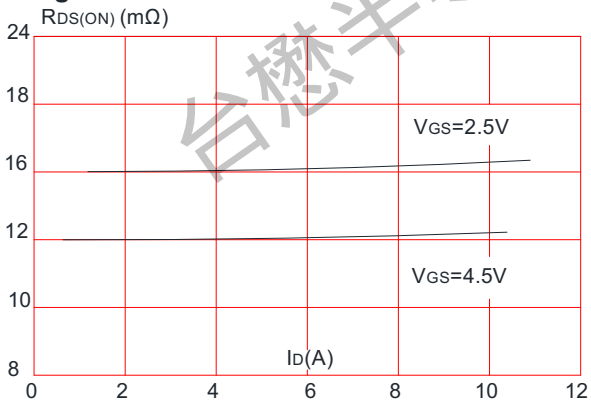
**Figure 1: Output Characteristics**



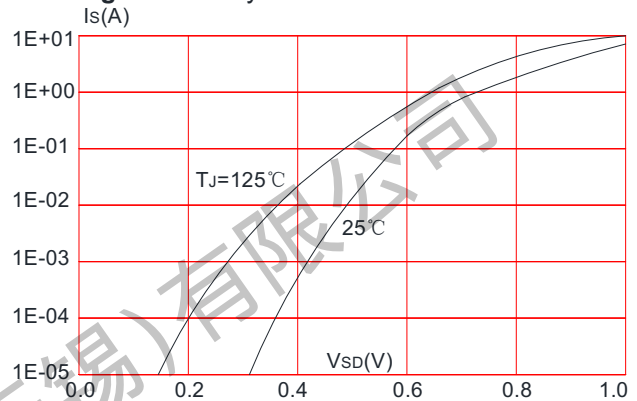
**Figure 2: Typical Transfer Characteristics**



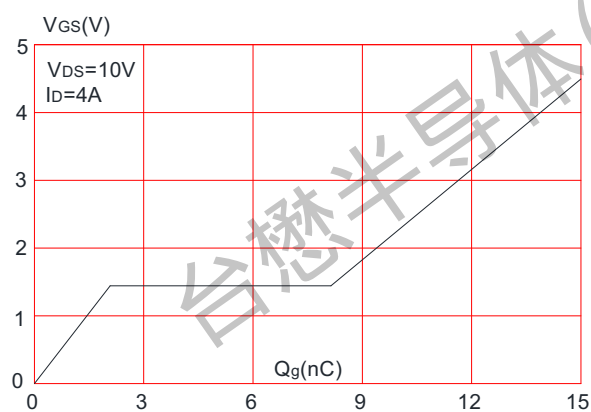
**Figure 3: On-resistance vs. Drain Current**



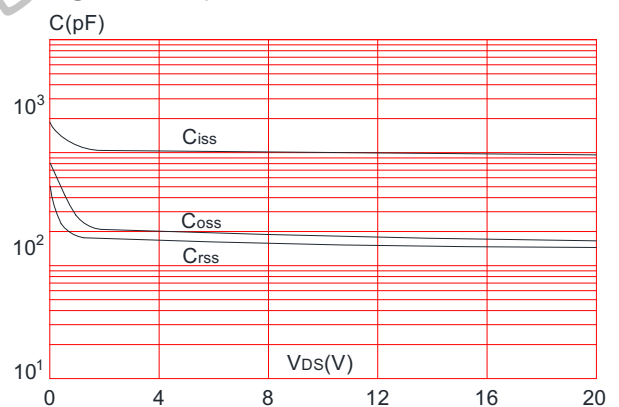
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**



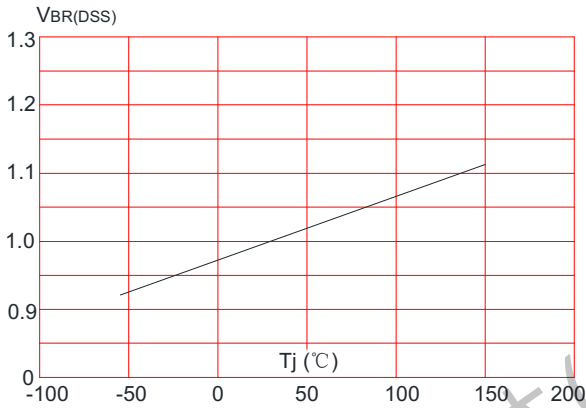
**Figure 6: Capacitance Characteristics**



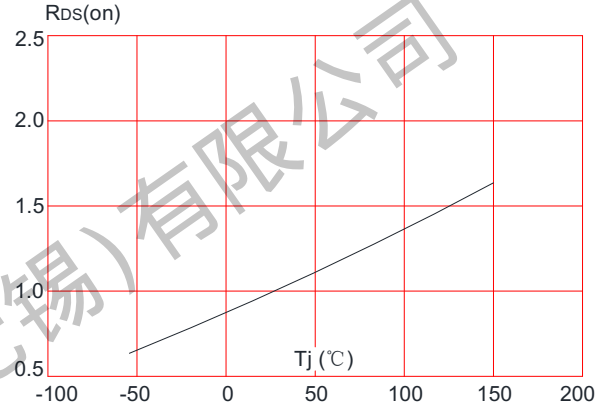
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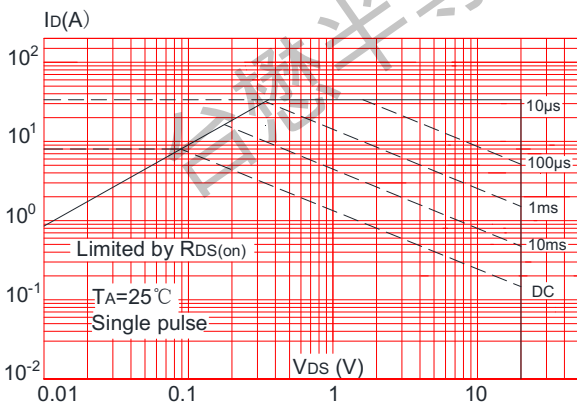
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



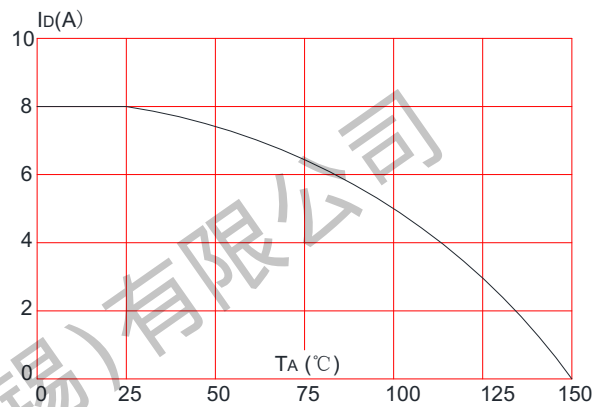
**Figure 8:** Normalized on Resistance vs. Junction Temperature



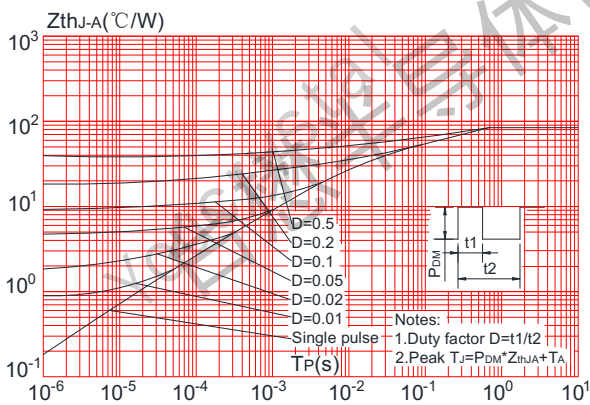
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

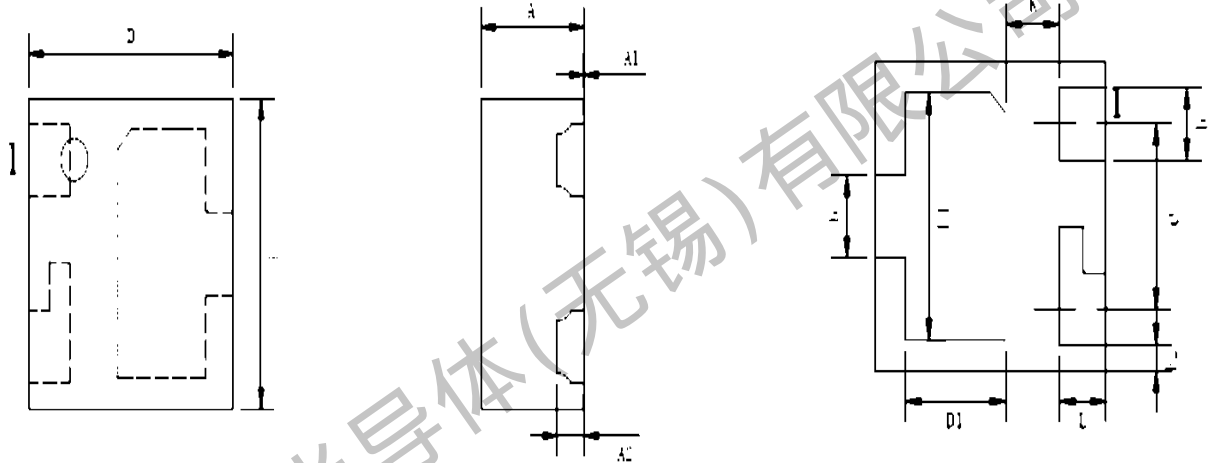




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**Package Mechanical Data:DFN1.5x1.5-3L**



SYMBOL	MILLMETER		
	MIN	NOM	MAX
<b>A</b>	—	—	<b>0.80</b>
<b>A1</b>	<b>0.00</b>	—	<b>0.05</b>
<b>A2</b>	<b>0.203 TIY</b>		
<b>b</b>	<b>0.30</b>	<b>0.35</b>	<b>0.40</b>
<b>D</b>	<b>1.45</b>	<b>1.50</b>	<b>1.55</b>
<b>D1</b>	<b>0.60</b>	<b>0.65</b>	<b>0.70</b>
<b>E</b>	<b>1.45</b>	<b>1.50</b>	<b>1.55</b>
<b>E1</b>	<b>1.15</b>	<b>1.20</b>	<b>1.25</b>
<b>E2</b>	<b>0.125 TIY</b>		
<b>e</b>	<b>0.90 BSC</b>		
<b>K</b>	<b>0.35 BSC</b>		
<b>L</b>	<b>0.25</b>	<b>0.30</b>	<b>0.35</b>



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Revision history:

Date	Rev	Description	Page
2023.05.25	23.05	Original	